

Ultra High Performance BGA Cooling Solutions w/ maxiGRIP[™] Attachment

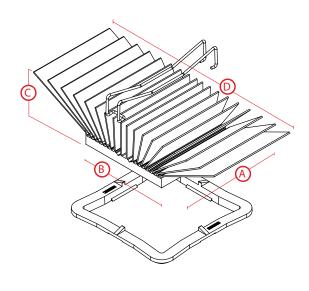
ATS PART # ATS-51250D-C2-R0

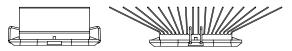
Features & Benefits

- maxiFLOW[™] design features a low profile, spread fin » array that maximizes surface area for more effective convection (air) cooling
- maxiGRIP[™] attachment applies steady, even pressure to » the component and does not require holes in the PCB
- Meets Telcordia GR-63-Core Office Vibration; ETSI 300 » 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards
- Comes preassembled with high performance, phase » changing, thermal interface material

Thermal Performance

Designed for low profile components from 1.5 to 2.99mm »





*Image above is for illustration purposes only.

AIR VELOCITY				THERMAL RESISTANCE		
	FT/MIN	M/S		°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)	
	200	1	.0	8.6	5.5	
	300 1.5		6.8			
	400 2.0		2.0	5.8		
500 2.5		2.5	5.2			
600		3	5.0	4.8		
	700 3.5		4.4			
800 4.0		.0	4.1			

Product Details

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
25 mm	25 mm	9.5 mm	36.4 mm	SAINT-GOBAIN C1100F	BLACK- ANODIZED

NOTES:

- Dimension C = heat sink height from bottom of the base to the top of the fin field.
- 2) ATS-51250D-C1-R0 is a subsitute item available utilizing an equivalent phase change material (Chomerics T766).
- Thermal performance data are provided for reference only. Actual performance may vary 3)
- by application. 4) ATS reserves the right to update or change its products without notice to improve the design or performance.
- Optional maxiGRIP™ Installation/Removal Tool Set P/N: MGT250 5)
- Contact ATS to learn about custom options available. 6)



For more information, to find a distributor or to place an order, visit www.gats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).

